Titles of Most Frequently Occurring Classifications of Patents Returned From A Search of 09698497 on October 25, 2001

3 438/692 (0 OR, 3 XR)

Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/689 CHEMICAL ETCHING

.Combined with the removal of material by

nonchemical means (e.g., ablating, abrading, etc.)

438/691 ... Combined mechanical and chemical material

removal

438/692 ...Simultaneous (e.g., chemical-mechanical polishing, etc.)

2 318/609 (0 OR, 2 XR)

Class 318: ELECTRICITY: MOTIVE POWER SYSTEMS

318/560 POSITIONAL SERVO SYSTEMS (E.G.,

SERVOMECHANISMS)

318/609 ."Reset" systems (P.I.)

2 330/252 (0 OR, 2 XR)

Class 330: AMPLIFIERS

330/250 WITH SEMICONDUCTOR AMPLIFYING DEVICE (E.G.,

TRANSISTOR)

330/252 .Including differential amplifier

2 365/201 (0 OR, 2 XR)

Class 365: STATIC INFORMATION STORAGE AND RETRIEVAL

365/189.01 READ/WRITE CIRCUIT

365/201 .Testing

2 438/424 (2 OR, 0 XR)

Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/400 FORMATION OF ELECTRICALLY ISOLATED LATERAL

SEMICONDUCTIVE STRUCTURE

438/424 .Grooved and refilled with deposited dielectric material

2 438/427 (0 OR, 2 XR)

Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/400 FORMATION OF ELECTRICALLY ISOLATED LATERAL SEMICONDUCTIVE STRUCTURE

438/424	.Grooved and refilled with deposited dielectric naterial
438/427	Refilling multiple grooves of different ridths or depths
	•
2 438/435 (0 Class 438:	OR, 2 XR) SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
Cluss 150.	SEMICONDUCTOR BEVIOLIMINOTHETOLICA. TROODS
	FORMATION OF ELECTRICALLY ISOLATED LATERAL SEMICONDUCTIVE STRUCTURE
438/424	.Grooved and refilled with deposited dielectric
438/435	naterialMultiple insulative layers in groove
2 438/443 (0	OR, 2 XR) SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
Class 436.	SEMICONDUCTOR DEVICE MANOFACTURING, I ROCESS
438/400	FORMATION OF ELECTRICALLY ISOLATED LATERAL
438/439	SEMICONDUCTIVE STRUCTURE .Recessed oxide by localized oxidation (i.e.,
	LOCOS)
438/443	Etchback of recessed oxide
2 438/700 (0	OR, 2 XR)
•	SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/689	CHEMICAL ETCHING
438/694	.Combined with coating step
438/700	Formation of groove or trench
2 438/701 (0	OR, 2 XR)
Class 438:	SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/689	CHEMICAL ETCHING
438/694	.Combined with coating step
438/700	Formation of groove or trench
438/701	Tapered configuration
2 438/702 (0	OR, 2 XR)
Class 438:	SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/689	CHEMICAL ETCHING
438/694	.Combined with coating step
438/700	Formation of groove or trench
438/702	Plural coating steps

2 438/792 (0 OR, 2 XR) Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/758 COATING OF SUBSTRATE CONTAINING SEMICONDUCTOR REGION OR OF SEMICONDUCTOR SUBSTRATE
438/778 .Insulative material deposited upon semiconductive substrate
438/791Silicon nitride formation
438/792Utilizing electromagnetic or wave energy (e.g., photo-induced deposition, plasma, etc.)
2 438/793 (0 OR, 2 XR)
Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/758 COATING OF SUBSTRATE CONTAINING SEMICONDUCTOR REGION OR OF SEMICONDUCTOR SUBSTRATE
438/778 .Insulative material deposited upon semiconductive substrate
438/791Silicon nitride formation
438/792Utilizing electromagnetic or wave energy
(e.g., photo-induced deposition, plasma, etc.) 438/793Organic reactant
438/793Organic reactant
2 438/794 (0 OR, 2 XR)
Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/758 COATING OF SUBSTRATE CONTAINING SEMICONDUCTOR REGION OR OF SEMICONDUCTOR SUBSTRATE
438/778 .Insulative material deposited upon semiconductive substrate
438/791Silicon nitride formation
438/794Organic reactant
2 700/83 (2 OR, 0 XR)
Class 700: DATA PROCESSING: GENERIC CONTROL SYSTEMS OR SPECIFIC APPLICATIONS
700/1 GENERIC CONTROL SYSTEM, APPARATUS OR PROCESS
700/83 .Having operator control interface (e.g., control/display console)

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FORMATION OF ELECTRICALLY ISOLATED LATERAL

SEMICONDUCTIVE STRUCTURE

438/400

438/424 .Grooved and refilled with deposited dielectric	
material 438/427Refilling multiple grooves of different	
widths or depths	
2 438/435 (0 OR, 2 XR) Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROC	ESS
438/400 FORMATION OF ELECTRICALLY ISOLATED LATER SEMICONDUCTIVE STRUCTURE	AL
438/424 .Grooved and refilled with deposited dielectric material	
Multiple insulative layers in groove	
2 438/443 (0 OR, 2 XR)	
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438/400 FORMATION OF ELECTRICALLY ISOLATED LATER SEMICONDUCTIVE STRUCTURE	AL
438/439 .Recessed oxide by localized oxidation (i.e.,	
LOCOS) 438/443Etchback of recessed oxide	
2 438/700 (0 OR, 2 XR) Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROC	ESS
438/689 CHEMICAL ETCHING	
438/694 .Combined with coating step 438/700Formation of groove or trench	
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438/689 CHEMICAL ETCHING	
438/694 .Combined with coating step	
438/700Formation of groove or trench 438/701Tapered configuration	
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2 438/702 (0 OR, 2 XR) Class 438: SEMICONDUCTOR DEVICE MANUFACTURING: PROC	ESS
438/689 CHEMICAL ETCHING	
438/694 .Combined with coating step	
438/700Formation of groove or trench 438/702Plural coating steps	
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700/83 .Having operator control interface (e.g.,
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Original Classifications

- 2 438/424
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Cross-Reference Classifications

- 3 438/692
- 2 318/609
- 2 330/252
- 2 365/201
- 2 438/427
- 2 438/435
- 2 438/443
- 2 438/700
- 2 438/701
- 2 438/702
- 2 438/792
- 2 438/793
- 2 438/794

Combined Classifications

- 3 438/692
- 2 318/609
- 2 330/252
- 2 365/201
- 2 438/424
- 2 438/427
- 2 438/435
- 2 438/443
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- 2 438/700
- 2 438/701
- 2 438/702
- 2 438/792
- 2 430/1/2
- 2 438/793
- 2 438/794
- 2 700/83

PLUS Search Results for S/N 09698497, Searched October 25, 2001